



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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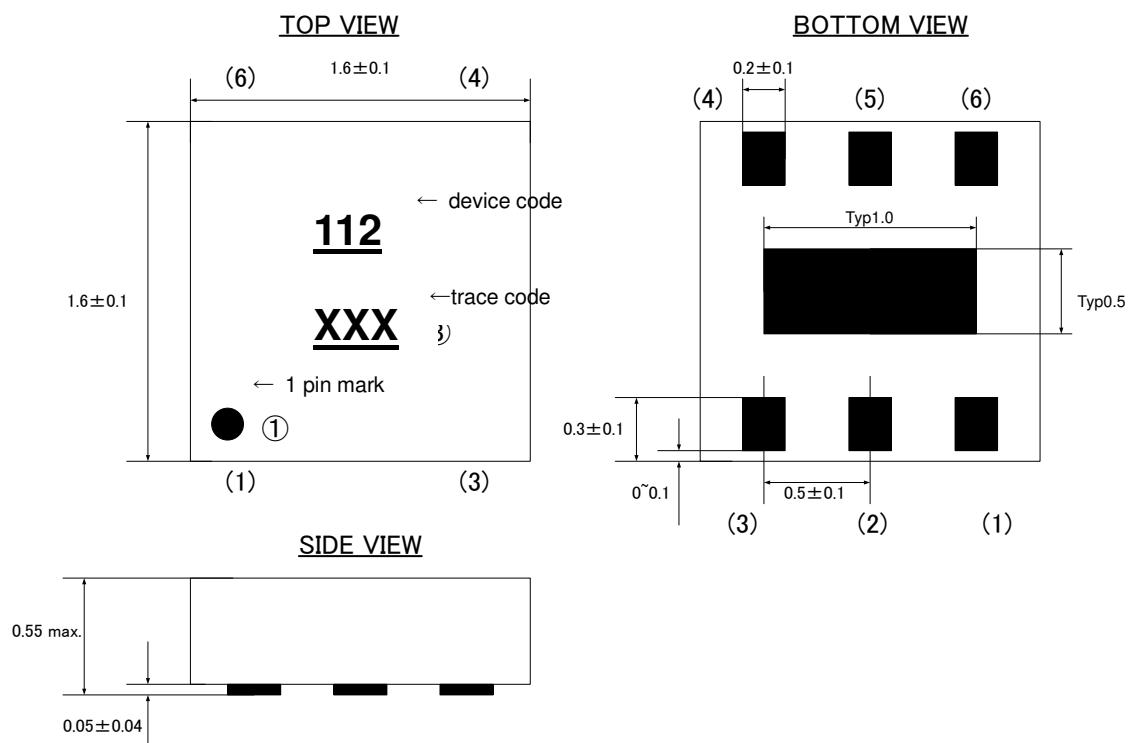
1. Application

- ESD Protection

2. Features

- IEC61000-4-2(ESD) $\pm 15\text{kV}$ (air), $\pm 12\text{kV}$ (contact)
- Low capacitance : 0.55pF typical
- Fast turn on and low clamping voltage
- For 2lines
- RoHS regulation conformity parts

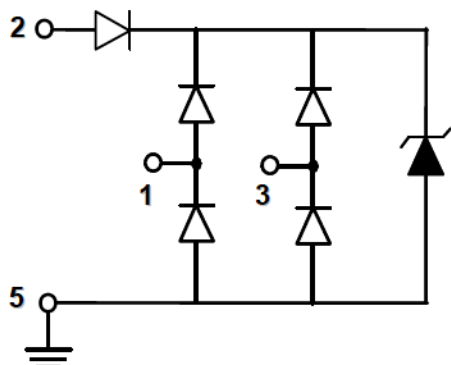
3. Mechanical details (dimensions : mm)



Pin configuration

No.	Terminal name
(1)	I/O 1
(2)	VDD
(3)	I/O 2
(4)	NC
(5)	GND
(6)	NC

4. Schematic



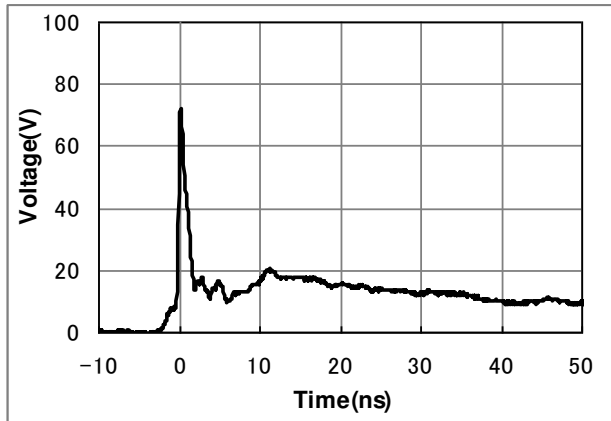
5. Maximum Ratings

Rating	Symbol	Value	Units
Operating voltage(VDD-GND)	V_{DC}	5.5	V
ESD per IEC 61000-4-2 (air)	V_{ESD}	± 15	kV
ESD per IEC 61000-4-2 (contact)		± 12	
Lead Soldering Temperature	T_{SOL}	260(10sec.)	$^{\circ}C$
Operating Temperature	T_{OP}	-40 to +85	$^{\circ}C$
Storage Temperature	T_{STO}	-40 to +125	$^{\circ}C$

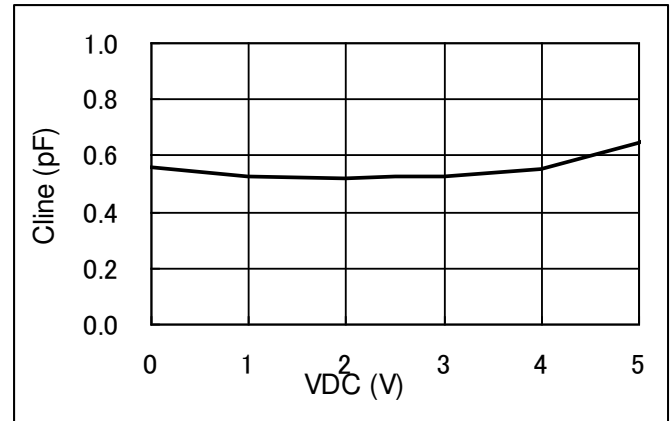
6. Electrical characteristics (T=25 $^{\circ}C$)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Leakage Current (I/O-GND)	I_{Leak}	$V_{pin5}=0V, V_{pin2}=5V, V_{CH}=0-5V$			1	μA
Breakdown Voltage	V_{BV}	$I_{BV} = 1mA$	6		9	V
Capacitance (I/O-GND)	C_{IN}	$V_{pin5} = 0V, V_{pin2} = 5V, V_{IN} = 2.5V,$ $f = 1MHz$		0.55		pF

7. Typical Characteristic

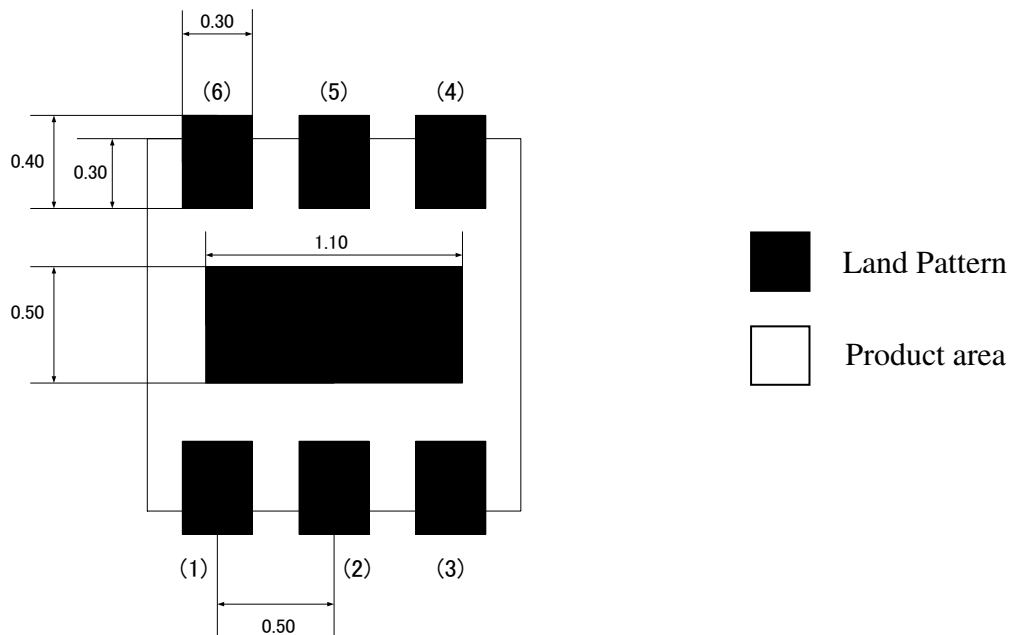


ESD Waveform (IEC61000-4-2:8kV Contact)



Voltage – Capacitance Characteristic

8. Soldering Footprint (dimensions : mm)

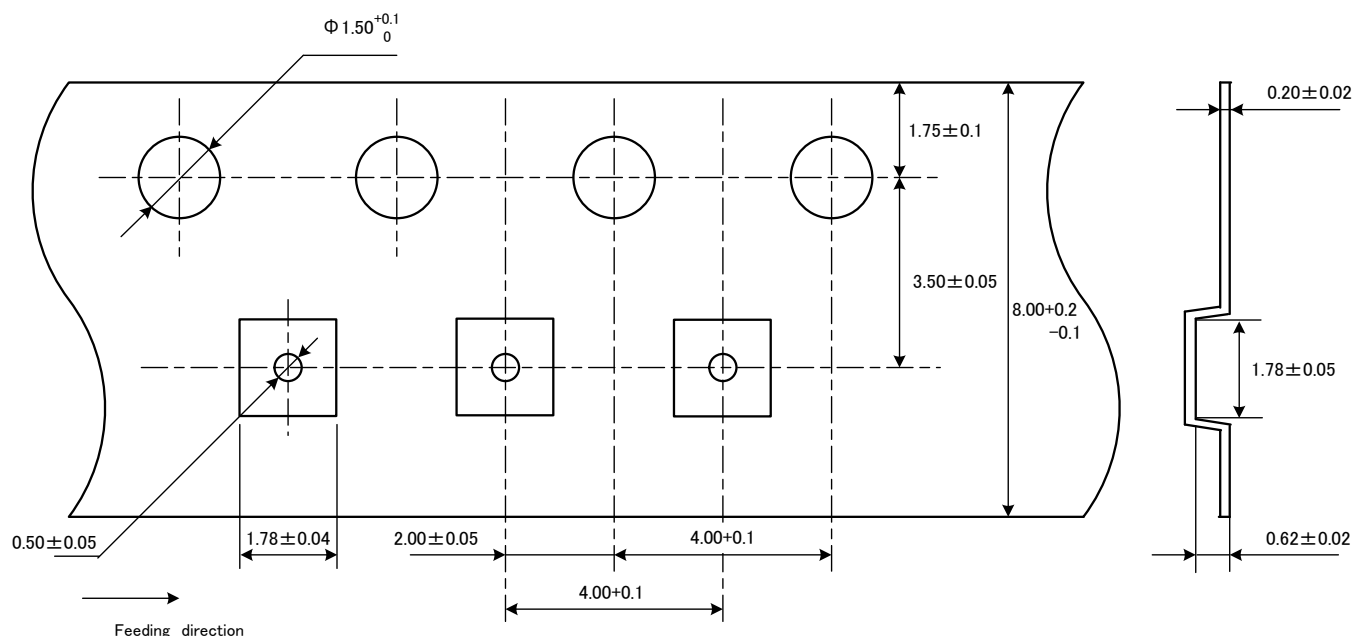


Notes : this land layout is for reference purpose only.

9. Taping Specification

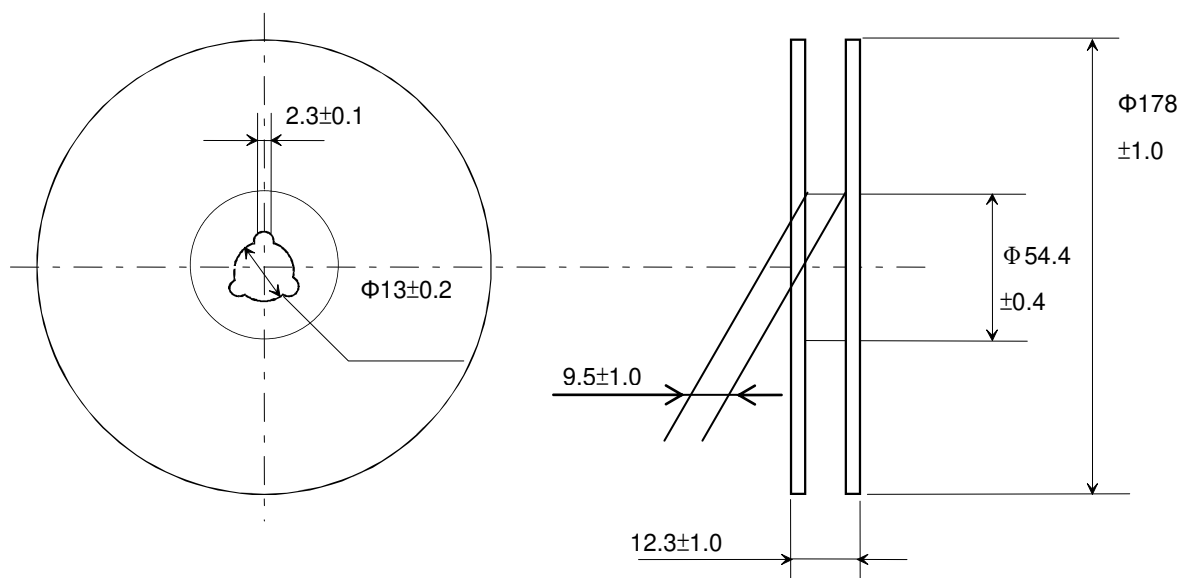
1) Dimensions of Tape (Plastic tape)

(in mm)



2) Dimensions of Reel

(in mm)



3) Packaging unit: 3,000 pcs / reel

Note:

1. This datasheet's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.